

ABSTRACT

Provided are a hollow sealing resin sheet which makes it possible not only to maintain a hollow structure even when a gap in the hollow structure has a width of about 100 μm , but also to produce a highly reliable hollow package by preventing the package from being warped; and a production method for a hollow package. The hollow sealing resin sheet of the present invention contains an inorganic filler in a content of 70 to 90% by volume both inclusive, and has: a minimum melt viscosity of 2000 to 20000 Pa·s both inclusive at temperatures of 60 to 130°C according to a dynamic viscoelasticity measurement; a storage modulus of 1 to 20 GPa both inclusive at 20°C after the resin sheet is thermally cured at 150°C for 1 hour; and a linear expansion coefficient of 5 to 15 ppm/K both inclusive at a glass transition temperature or lower after the resin sheet is thermally cured at 150°C for 1 hour.